

| L Number | Hits | Search Text  | DB  | Time stamp          |
|----------|------|--|---|---------------------|
| 20       | 1    | 5864278.pn.  | USPAT;<br>US-PGPUB                                      | 2003/06/06<br>13:01 |
| -        | 17   | (temperature\$1dependent).ti. and<br>(marcel).in.  | USPAT;<br>US-PGPUB                                      | 2003/05/31<br>11:24 |
| -        | 395  | (temperature\$1dependent).ti. ahesive and<br>stamp\$3 and heat\$3 and seal\$3  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/05/31<br>11:31 |
| -        | 12   | ((temperature\$1dependent).ti. ahesive and<br>stamp\$3 and heat\$3 and seal\$3) and<br>(moisture dust)   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/05/31<br>11:27 |
| -        | 1    | temperature\$1dependent and ahesive and<br>heat\$3 and seal\$3   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/05/31<br>11:51 |
| -        | 2    | 6282409.pn.  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/05/31<br>11:34 |
| -        | 2    | 6051169.pn.  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/05/31<br>11:34 |
| -        | 1502 | stamp\$3 and (moisture dust) and cover\$3<br>and adhesive and heat\$3 and seal\$3  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/05/31<br>12:11 |
| -        | 8    | (stamp\$3 and (moisture dust) and cover\$3<br>and adhesive and heat\$3 and seal\$3) and<br>temperature\$1dependent   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/05/31<br>11:54 |
| -        | 553  | (stamp\$3 and (moisture dust) and cover\$3<br>and adhesive and heat\$3 and seal\$3) and<br>join\$3 and clos\$3 and cur\$3  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/05/31<br>11:59 |
| -        | 197  | ((stamp\$3 and (moisture dust) and cover\$3<br>and adhesive and heat\$3 and seal\$3) and<br>join\$3 and clos\$3 and cur\$3) and circuit  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/05/31<br>12:06 |
| -        | 185  | ((stamp\$3 and (moisture dust) and cover\$3<br>and adhesive and heat\$3 and seal\$3) and<br>join\$3 and clos\$3 and cur\$3) and switch\$3  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/05/31<br>12:06 |
| -        | 4528 | join\$3 and clos\$3 and cur\$3 and (moisture<br>dust) and cover\$3 and adhesive and heat\$3<br>and seal\$3   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/05/31<br>12:12 |
| -        | 904  | (join\$3 and clos\$3 and cur\$3 and<br>(moisture dust) and cover\$3 and adhesive<br>and heat\$3 and seal\$3) and protect\$3 and<br>connect\$3 and switch\$3  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/05/31<br>12:13 |
| -        | 218  | ((join\$3 and clos\$3 and cur\$3 and<br>(moisture dust) and cover\$3 and adhesive<br>and heat\$3 and seal\$3) and protect\$3 and<br>connect\$3 and switch\$3) and press\$3 and<br>electric\$4 and dip\$4 and fill\$3 | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/05/31<br>12:16 |

|   |     |  |   |                     |
|---|-----|--|---|---------------------|
| - | 107 | ((join\$3 and clos\$3 and cur\$3 and (moisture dust) and cover\$3 and adhesive and heat\$3 and seal\$3) and protect\$3 and connect\$3 and switch\$3) and press\$3 and electric\$4 and dip\$4 and fill\$3) and circuit\$3 | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/05/31<br>12:26 |
| - | 14  | adhesive with cur\$3 and join\$3 and hous\$3 and cover\$3 and heat\$3 and seal\$3 and (dust moisture) and clos\$3 and switch\$3 with mechanism   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/05/31<br>13:36 |
| - | 2   | "19757023"   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/05/31<br>13:40 |
| - | 0   | "29605048"   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/05/31<br>13:44 |
| - | 8   | "4139091"  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/05/31<br>13:44 |
| - | 43  | 29/622,623.ccls. and 337/\$.ccls. and adhesive   | USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB              | 2003/06/02<br>15:34 |
| - | 45  | 29/622,623.ccls. and adhesive and seal\$3 and cur\$3   | USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB              | 2003/06/02<br>15:37 |
| - | 4   | 29/dig?1.ccls. and adhesive and seal\$3 and cur\$3   | USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB              | 2003/06/02<br>15:38 |
| - | 2   | 337/33\$.ccls. and adhesive and seal\$3 and cur\$3   | USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB              | 2003/06/02<br>15:39 |
| - | 94  | 337/\$.ccls. and adhesive and seal\$3 and cur\$3   | USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB              | 2003/06/02<br>15:42 |
| - | 369 | 156/292,293,305.ccls. and adhesive and seal\$3 and cur\$3  | USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB              | 2003/06/02<br>15:42 |
| - | 21  | (156/292,293,305.ccls. and adhesive and seal\$3 and cur\$3) and switch\$3  | USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB              | 2003/06/02<br>15:45 |
| - | 94  | 337/\$.ccls. and switch\$3 and adhesive and bimetal\$4   | USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB              | 2003/06/02<br>15:46 |
| - | 33  | (337/\$.ccls. and switch\$3 and adhesive and bimetal\$4) and cover\$3 and cur\$3   | USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB              | 2003/06/02<br>15:48 |
| - | 69  | (337/\$.ccls. and switch\$3 and adhesive and bimetal\$4) and cover\$3  | USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB              | 2003/06/02<br>15:48 |